

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,078,819 B2  
APPLICATION NO. : 09/854269  
DATED : July 18, 2006  
INVENTOR(S) : Thomas H. DiStefano

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the cover:

In the Abstract, line 6, "but provides thermal" should read -- but can provide thermal --.

Column 1, lines 65-66, "interfaces with the contact pads, produce" should read -- interface with the contact pads, producing --.

Column 2, line 47, "as a" should read -- as an --.

Column 3, line 5, "chip does not" should read -- chip do not --.

Column 3, line 24, "thereon provides" should read -- thereon, provides --.

Column 6, line 1, "and the amount of using" should read -- and mounted using --.

Column 7, line 26, "via-liners can" should read -- via-liners, can --.

Column 9, line 4, "that is in inert" should read -- that it is inert --.

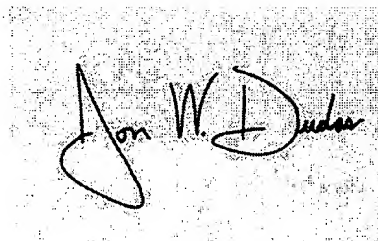
Column 10, line 36, "interposer 201" should read -- interposer 20 --.

Column 10, line 51, "130 SO" should read -- 130 so --.

Column 14, line 2, "so that, said" should read -- so that said --.

Signed and Sealed this

Thirtieth Day of January, 2007

A handwritten signature in black ink, appearing to read "Jon W. Dudas", is written over a light gray, textured rectangular background.

JON W. DUDAS  
*Director of the United States Patent and Trademark Office*